

## AMENDMENTS TO THE SPECIFICATION

Please add new paragraph [0024.1] as follows:

**[0024.1] Figure 19 shows a module of a second substrate package on the substrate package of Figure 17 with no gap thickness between the connective structures.**

Please amend paragraph [0041] as follows:

**[0041] Figure 18 shows a multi-chip module with structure 600 connected to structure 500 through fusible masses 680. In this embodiment, where encapsulant surrounds 75 to 90 percent or more of fusible masses 580, the connection of structure 600 to structure 500 leaves at least minimal gap thickness,  $T_3$ , if any, between the connected structures. In another embodiment, the material for encapsulant 590 may be selected so that the material does not set until the structures (e.g., structure 600 and structure 500) are connected together. For example, an encapsulant of a polymer material may be selected such that 60 to 90 percent of a theoretical cross-link density is achieved prior to the connection of substrate 600 to substrate 500 through fusible masses 580. Once the connection is made, encapsulant 590 that is present in an amount sufficient to contact substrate 610 (e.g.,  $T_3$  is zero) allows the encapsulant to bond these structures together. A suitable material for encapsulant 590, in this example, is a material that has a curing chemistry such that the material completes its cross-linking reaction at a time and temperature above that it needed for solder metallurgical joint formation. Figure 19 shows a multi-chip module similar to Figure 18 with  $T_3$  of zero or no gap between structure 600 and structure 500.**